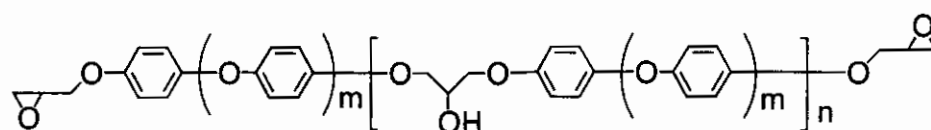


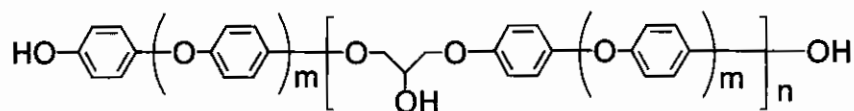
Abstract

Disclosed is an epoxy resin composition that cures with high thermal conductivity and low thermal expansion and is capable of dissipating heat efficiently and displaying good dimensional stability when applied to encapsulation of semiconductor devices or to printed wiring boards. The epoxy resin composition is formulated from epoxy resins 50 wt% or more of which is a diphenyl ether type epoxy resin represented by the following general formula (1)



(1)

(wherein n is a number of ≥ 0 and m is an integer of 1-3) and curing agents 20 wt% or more of which is a diphenyl ether type phenolic resin represented by the following general formula (2)



(2)

(wherein n is a number of ≥ 0 and m is an integer of 1-3).